

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance	R <sub>θJL</sub>	15	°C/W	
Junction-to-ambient thermal resistance	R <sub>eja</sub>	40	°C/W	

PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage per diode <sup>(1)</sup>	DBLS151G DBLS152G DBLS153G DBLS154G DBLS155G DBLS156G DBLS157G DBLS158G DBLS158G	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 25°C	V <sub>F</sub>	-	1.10	V
Reverse current @ rated $V_R$ per diode <sup>(2)</sup>		$T_J = 25^{\circ}C$		-	2	μA
		T <sub>J</sub> = 125°C	I <sub>R</sub>	-	500	μA

#### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE <sup>(1)(2)</sup>	PACKAGE	PACKING	
DBLS15xG	DBLS	1,500 / Tape & Reel	
DBLS15xGH	DBLS	1,500 / Tape & Reel	

Notes:

- 1. "x" defines voltage from 50V(DBLS151G) to 1400V(DBLS159G)
- 2. "H" means AEC-Q101 qualified



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### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

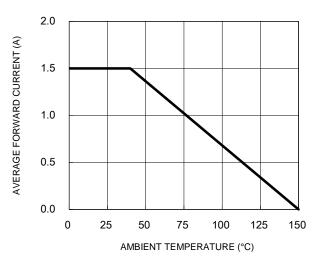


Fig.1 Forward Current Derating Curve

#### **Fig.3 Typical Reverse Characteristics**

**Fig.4 Typical Forward Characteristics** 10 100 INSTANTANEOUS REVERSE CURRENT (µA) INSTANTANEOUS FORWARD CURRENT (A) DBLS151G - DBLS157G T<sub>1</sub>=125°C 10 1 1 DBLS158G - DBLS159G 0.1 T,=25°C Ξ Pulse width 300µs 1% duty cycle 0.1 0.01 0.7 0.8 0.6 0.9 1.0 1.1 1.2 1.3 1.4 1.5 10 20 30 40 50 60 70 80 90 100 PERCENT OF RATED PEAK REVERSE VOLTAGE (%) FORWARD VOLTAGE (V)

100

10

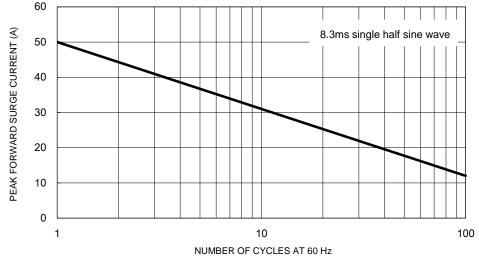
1

1

f=1.0MHz Vsig=50mVp-p

CAPACITANCE (pF)

# Fig.5 Maximum Non-Repetitive Forward Surge Current



**Fig.2 Typical Junction Capacitance** 

10

REVERSE VOLTAGE (V)

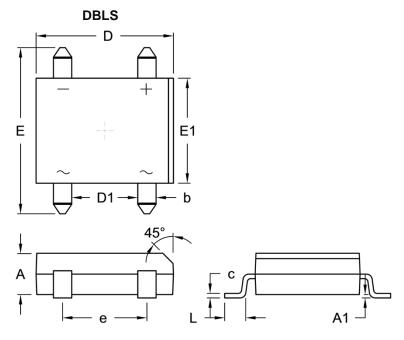
100



# DBLS151G - DBLS159G

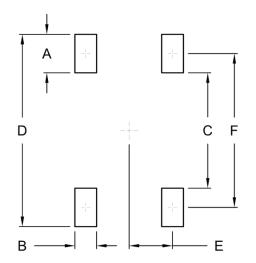
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## PACKAGE OUTLINE DIMENSIONS



DIM.	Unit (mm)		Unit (inch)	
Divi.	Min.	Max.	Min.	Max.
A	2.40	2.60	0.094	0.102
A1	0.076	0.330	0.003	0.013
b	1.02	1.20	0.040	0.047
с	0.22	0.33	0.009	0.013
D	8.13	8.51	0.320	0.335
D1	3.90	4.10	0.154	0.161
E	9.80	10.30	0.386	0.406
E1	6.20	6.50	0.244	0.256
е	5.00	5.20	0.197	0.205
L	1.02	1.53	0.040	0.060

## SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.30	0.091
В	1.30	0.051
С	6.90	0.272
D	11.50	0.453
E	2.60	0.102
F	9.20	0.362

## **MARKING DIAGRAM**



- P/N = Marking Code
- G = Green Compound
- YW = Date Code
- F = Factory Code



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